

PCI-SIG® Highlights PCIe Technology as the Interconnect of Choice for HPC at SC23

Members showcasing PCIe® technology demos and new PCI Express Cable naming scheme announced

PCI-SIG announced the new naming scheme for PCIe Internal and External Cables will be **CopprLink™**. The PCIe 5.0 and PCIe 6.0 Internal and External Cable Specifications are currently in development and are targeted for release in 2024.

View the PCIe technology demos at SC23

WHEN: Monday, November 13 – Thursday, November 16, 2023

WHERE: [SC23](#) – Colorado Convention Center, Denver, CO

- PCI-SIG Booth #1401

WHO: Members of [PCI-SIG](#), the consortium that owns and manages PCI specification as open industry standards, will be showcasing PCI Express® (PCIe®) technology demonstrations at SC23 in booth #1401.

WHAT: PCI-SIG invites SC23 attendees to visit booth #1401 to view the demos and learn more about the PCIe technology ecosystem. The demonstrations highlight the role of PCIe technology as the high-speed I/O interconnect of choice for High Performance Computing (HPC) applications. The participating companies include [Astera Labs](#), [Dolphin Interconnect Solutions](#), [Synopsys](#) and [Tektronix](#).

SCHEDULE A BRIEFING: Members of the media interesting in learning more about the PCIe Cabling Specifications and other technology update, please contact pr@pcisig.com to schedule a briefing.